

From	To	Room/Event				Type
<b>Time</b>		<b>Day 1: Monday — October 7, 2024</b>				
3:00PM	6:00PM	Location: California Ballroom Foyerr, Mezzanine Level				ASME Meetings
		Registration Opens				
6:30PM	8:30PM	Location: TBD				
		Leadership Dinner - By invitation Only				
<b>Time</b>		<b>Day 2: Tuesday — October 8, 2024</b>				
From	To	Room/Event				Type
7:45AM	8:00AM	Room: California DE				ASME Meetings
		InterPACK'24 -Opening Remarks by Prof. Pradeep Lall				
8:00AM	8:45AM	Room: California Ballroom , Salons FGHI				Plenary Speaker
		OUSD IBAS RESHAPE Project - Matthew Walsh				
8:45AM	9:30AM	The Use of Additive Hybrid Electronics as a Key Element in the National Strategy for Advanced Packaging - Art Wall				
9:30AM	10:45AM	Room: California Ballroom, Salon C	Room: California Ballroom, Salon B	Room: California Ballroom, Salon K	Room: California Ballroom, Salon A	Technical Sessions
		03-01: Electronics Packaging - Electrical Design	02-01: Data Centers and Modular Edge Systems - I	07-01: Transportation Systems, AI and Machine Learning - I	Reliability of Additively Manufacturing Flexible and Stretchable Electronics – Experiments, Models, and Applications	Workshops
10:45AM	11:00AM	Coffee Break/Exhibitors - California Ballroom, Mezzanine Foyer				
11:00AM	12:15PM	Room: California Ballroom, Salon C	Room: California Ballroom, Salon L	Room: California Ballroom, Salon M	Room: California Ballroom, Salon A	Technical Sessions
		03-02: Electronics Packaging - Components	04-01: Power/RF Electronics and Photonics - I	06-01: FHE Design & Reliability	Data Center and Telecom Challenges and Opportunities	Panel
12:15PM	1:30PM	Room: California Ballroom, Salons FGHI				Lunch Presentations
		Lunch: Avram Bar-Cohen Award				
1:30PM	2:15PM	Room: California Ballroom, Salon D		Room: California Ballroom, Salon E		Track Keynotes

		Passive Two-Phase Cooling of Electronics and Energy Efficiency		Efficient Energy Systems		Tutorials	
2:15PM	2:30PM	Coffee Break/Exhibitors - California Ballroom, Mezzanine Foyer					
2:30PM	3:45PM	Room: California Ballroom, Salon C	Room: California Ballroom, Salon B	Room: California Ballroom, Salon L	Room: California Ballroom, Salon A	Technical Sessions	
		03-04: Electronics Packaging - Stress and Reliability - I	02-02: Data Centers and Modular Edge Systems - II	04-02: Power/RF Electronics and Photonics - II	Machine Learning for Electronics	Panel	
3:50PM	5:15PM	Room: California Ballroom, Salon C	Room: California Ballroom, Salon M	Room: California Ballroom, Salon K	Room: California Ballroom, Salon A	Technical Sessions	
		03-05: Electronics Packaging - Stress and Reliability- II	06-02: Advanced Materials & Processes for Printed Electronics - I	K16 Mentorship	Women in Engineering	Workshops	
		Room: California Ballroom, Salon L				Short Course	
Short Course - Efficient Thermal Simulations Using Compact Models							
5:45PM	6:45PM	Room: Salon San Jose Ballroom					Student Posters
		Interactive Poster Session					
6:45PM	7:15PM	Room California Ballroom, Salon D					ASME Meetings
		JEP Editorial Meeting					
7:15PM	8:45PM	Room: California Ballroom, Salon D					ASME Meetings
		K-16 Committee Meeting (Open)					
8:45PM	9:15PM	Room: California Ballroom, Salon D					ASME Meetings
		K-16 Committee Meeting (Closed)					

Time		Day 3: Wednesday — October 9, 2024				
From	To	Room/Event				Type
8:00AM	9:30AM	Room: California Ballroom , Salons FGHI				Plenary Speaker
		2.5D/3D Integration for High-Speed Light Engines - Radha Nagarajan				
9:30AM	10:45AM	Room: California Ballroom, Salon C	Room: California Ballroom, Salon A	Room: California Ballroom, Salon M	Room: Salon K	Technical Sessions
		03-06: Electronics Packaging - Stress and Reliability - III	01-01: Heterogeneous Integration	06-04: Materials & Processes for RF Electronics	Liquid-Cooling and Heat Reuse Technologies	Tutorials
10:45AM	11:00AM	Coffee Break/Exhibitors - California Ballroom, Mezzanine Foyer				

11:00AM	12:15PM	Room: California Ballroom, Salon C	Room: California Ballroom, Salon B	Room: California Ballroom, Salon M	Room : California Ballroom, Salon K	Technical Sessions
		03-07: Electronics Packaging - Stress and Reliability - IV	02-03: Data Centers and Modular Edge Systems - III	06-05: FHE Applications & Processing	Advancing Electronics Packaging and Heterogeneous Integration: Insights from Interpack 2024	Workshop
12:15PM	1:30PM	Room: California Ballroom, Salons FGHI				Lunch Presentations
		Lunch: InterPACK'24 Allan Kraus Award				
1:30PM	2:15PM	Room: California Ballroom, Salon D		Room: California Ballroom, Salon E		Track Keynotes
		Size and Timescale Matching for Transient-Aware Thermal Management		AI/ML and Industry Trends		Tutorials
2:15PM	2:30PM	Coffee Break/Exhibitors - California Ballroom, Mezzanine Foyer				
2:30PM	3:45PM	Room: California Ballroom, Salon C	Room: California Ballroom, Salon B	Room: California Ballroom, Salon K	Room : California Ballroom, Salon A	Technical Sessions
		03-08: Electronics Packaging - Reliability	02-04: Data Centers and Modular Edge Systems - IV		Thermal/Mechanical/Electrical Challenges and Opportunities for Mobile/Wireless/AI/IoT/Automotive and Higher Power Computing Devices	Panel
3:50PM	5:15PM	Room: California Ballroom, Salon L	Room: California Ballroom, Salon M	Room: California Ballroom, Salon C		Technical Sessions
		05-03: Multiscale Thermal Transport and Energy Storage - III	06-06: Advanced Materials & Processes for Printed Electronics - II	03-09: Electronics Packaging - Thermal - I		Workshops
6:00PM	6:30PM	Room: California Ballroom, Salon D				ASME Meetings
		InterPACK Meeting (Closed)				
6:30PM	7:00PM	Room: California Ballroom, Salon D				ASME Meetings
		InterPACK Meeting (Open)				
7:00PM	8:00PM	Room: California Ballroom, Salon D				ASME Meetings
		EPPD Meeting (Open)				

Time		Day 4: Thursday — October 10, 2024				
From	To	Room/Event				Type
8:00AM	8:45AM	Room: California Ballroom , Salons FGHI				Plenary Speaker
		ARPA-E COOLERCHIPS Technology for a Future of Energy Efficient High Power Density/AI Data Centers - Peter de Bock				

8:45AM	9:30AM	Data Center Industry's Supply Chain Readiness and Scalability for Liquid Cooling - Ani Natekar				
9:30AM	10:45AM	Room: California Ballroom, Salon C	Room: California Ballroom, Salon L	Room: California Ballroom, Salon B	Room: California Ballroom, Salon M	Technical Sessions
		03-10: Electronics Packaging - Thermal - II (Two-phase)	05-01: Multiscale Thermal Transport and Energy Storage - I	02-05: Data Centers and Modular Edge Systems V	Status, Challenges, and Opportunities in Electronics Packaging from a Government/Lab Perspective	Workshop
10:45AM	11:00AM	Coffee Break/Exhibitors - California Ballroom, Mezzanine Foyer				
11:00AM	12:15PM	Room: California Ballroom, Salon C	Room: California Ballroom, Salon L	Room: California Ballroom, Salon B	Room: California Ballroom, Salon M	Technical Sessions
		03-11: Electronics Packaging - Thermal - III	05-02: Multiscale Thermal Transport and Energy Storage - II	02-07: Data Centers and Modular Edge Systems VII	Additive Manufacturing for Domestic Electronics Packaging	Panel
12:15PM	1:30PM	Room: California Ballroom, Salons FGHJ				Lunch Presentations
		Lunch: ASME Worcester Reed Warner Medal + InterPACK'24 Awards (Nasser Grayeli Poster, EPPD, JEP)				
1:30PM	2:15PM	Room: California Ballroom, Salon D		Room: California Ballroom, Salon E		Track Keynotes
		Wearable Ultrasound Technology		Additive Manufacturing for Electronic Devices and Interconnects		Tutorials
2:15PM	2:30PM	Coffee Break/Exhibitors - California Ballroom, Mezzanine Foyer				
2:30PM	3:45PM	Room: California Ballroom, Salon C	Room: California Ballroom, Salon B	Room: California Ballroom, Salon M	Room: California Ballroom, Salon A	Technical Sessions
		03-12: Electronics Packaging - Thermal IV (Single Phase Convection)	02-06: Data Centers and Modular Edge Systems -VI	06-07: FHE Printing & Packaging	Two-phase Flow for Electronics Cooling	Panel
3:50PM	5:15PM				Room: California Ballroom, Salon M	Technical Sessions
					06-03: Printed Electronics for Wearables & Health	Workshop